



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS716G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001116394						
<b>Package</b>		PG-DSO-20-32		<b>Weight*</b>		478.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.009	1.46	1.46	14640	14640
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5977	
wire	non noble metal	copper	7440-50-8	116.197	24.27	24.91	242692	249043
	non noble metal	aluminium	7429-90-5	0.422	0.09	0.09	882	882
	encapsulation	organic material	carbon black	1333-86-4	0.692	0.14		1445
	plastics	epoxy resin	-	31.815	6.64		66449	
	inorganic material	silicondioxide	60676-86-0	313.305	65.45	72.23	654379	722273
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5735	5735
plating	non noble metal	nickel	7440-02-0	0.341	0.07		713	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		2	
glue	non noble metal	silver	7440-22-4	1.177	0.25	0.32	2458	3173
	plastics	epoxy resin	-	0.356	0.07		744	
	noble metal	silver	7440-22-4	1.680	0.35	0.42	3510	4254
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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